

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S51	169	arrow with orientation with (box or container)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 09:55
S52	2	(arrow with orientation with (box or container)) and semiconductor and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 09:57
S53	3	((arrow or sign or description) with orientation with (box or container)) and semiconductor and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 09:58
S54	2	(arrow or sign or description) with shipping with orientation with (box or container)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 10:00
S55	124	shipping with (box or container) with semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 10:01
S56	71	shipping with (box or container) with semiconductor with wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 10:18
S59	227	shipping adj (box or container) with orient\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 10:20
S60	1	shipping adj (box or container) with orient\$5 with arrow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 10:46

S61	54	shipping adj (box or container) with semiconductor with wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 11:56
S63	15	(solder adj bumps) and semiconductor and wafer and (interconnection with conductor with material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 12:16
S64	7	(solder adj bumps) and (flip adj chip) and semiconductor and wafer and (interconnection with conductor with material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:03
S66	8	(solder adj (bumps or ball)) and (flip adj chip) and semiconductor and wafer and (interconnection with conductor with material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:04
S67	72	(solder adj (bumps or ball)) and (flip adj chip) and semiconductor and separator	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:05
S68	17	(solder adj (bumps or ball)) and (flip adj chip) and semiconductor and separator and stack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:50
S71	287	(solder adj (bumps or ball)) and (flip adj chip adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:50
S73	213	(solder adj (bumps or ball)) and (flip adj chip adj bump) and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/26 13:51